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Nota di contenuto	LED Packaging for Lighting Applications: Design, Manufacturing and Testing; Contents; Foreword By Magnus George Craford; Foreword By C. P. Wong; Foreword By B. J. Lee; Preface; Acknowledgments; About the Authors; 1 Introduction; 1.1 Historical Evolution of Lighting Technology; 1.2 Development of LEDs; 1.3 Basic Physics of LEDs; 1.3.1 Materials; 1.3.2 Electrical and Optical Properties; 1.3.3 Mechanical and Thermal Properties; 1.4 Industrial Chain of LED; 1.4.1 LED Upstream Industry; 1.4.2 LED Midstream Industry; 1.4.3 LED Downstream Industry; 1.5 Summary; References 2 Fundamentals and Development Trends of High Power LED Packaging 2.1 Brief Introduction to Electronic Packaging; 2.1.1 About Electronic Packaging and Its Evolution; 2.1.2 Wafer Level Packaging, More than Moore, and SiP; 2.2 LED Chips; 2.2.1 Current Spreading Efficiency; 2.2.2 Internal Quantum Efficiency; 2.2.3 High Light Extraction Efficiency; 2.3 Types and Functions of LED Packaging; 2.3.1 Low Power LED Packaging; 2.3.2 High Power LED Packaging; 2.4 Key

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5.2 High Power LED Packaging Reliability Test

Sommario/riassunto

"This book provides quantitative methods for optical, thermal, reliability modelling and simulation so that predictive quantitative modelling can be achieved"--
